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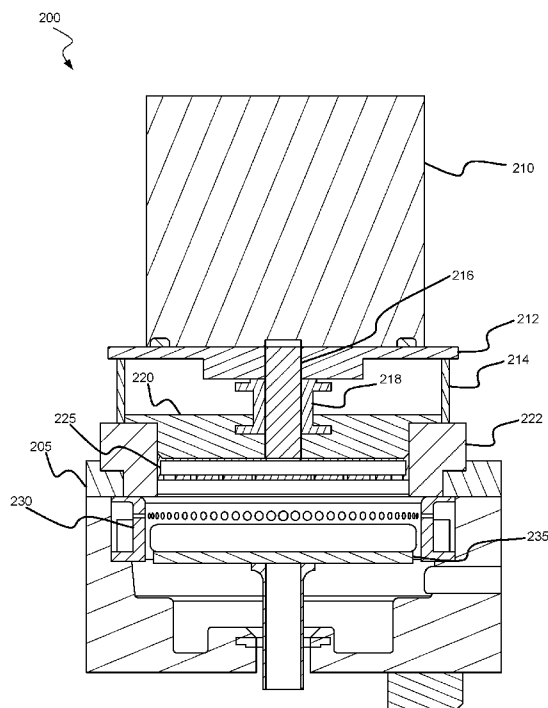


FIG. 2

(57) Abstract: Semiconductor systems and methods may include a semiconductor processing chamber having a gas box defining an access to the semiconductor processing chamber. The chamber may include a spacer characterized by a first surface with which the gas box is coupled, and the spacer may define a recessed ledge on an interior portion of the first surface. The chamber may include a support bracket seated on the recessed ledge that extends along a second surface of the spacer. The chamber may also include a gas distribution plate seated on the support bracket.



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SYSTEMS AND METHODS FOR IMPROVED SEMICONDUCTOR ETCHING AND COMPONENT PROTECTION

TECHNICAL FIELD

5 **[0001]** The present technology relates to systems and methods for etching semiconductor materials. More specifically, the present technology relates to chambers and methods for etching with improved degradation characteristics for chamber components.

BACKGROUND

10 **[0002]** Integrated circuits are made possible by processes which produce intricately patterned material layers on substrate surfaces. Producing patterned material on a substrate requires controlled methods for removal of exposed material. Chemical etching is used for a variety of purposes including transferring a pattern in photoresist into underlying layers, thinning layers, or thinning lateral dimensions of features already present on the surface. Often it is desirable to
15 have an etch process that etches one material faster than another facilitating, for example, a pattern transfer process. Such an etch process is said to be selective to the first material. As a result of the diversity of materials, circuits, and processes, etch processes have been developed with a selectivity towards a variety of materials.

20 **[0003]** Etch processes may be termed wet or dry based on the materials used in the process. A wet HF etch preferentially removes silicon oxide over other dielectrics and materials. However, wet processes may have difficulty penetrating some constrained trenches and also may sometimes deform the remaining material. Dry etches produced in local plasmas formed within the substrate processing region can penetrate more constrained trenches and exhibit less deformation of delicate remaining structures. However, local plasmas may damage the substrate
25 through the production of electric arcs as they discharge. Additionally, plasma effluents can damage chamber components that may require replacement or treatment.

[0004] Thus, there is a need for improved systems and methods that can be used to produce high quality devices and structures. These and other needs are addressed by the present technology.

SUMMARY

[0005] Semiconductor systems and methods may include a semiconductor processing chamber having a gas box defining an access to the semiconductor processing chamber. The chamber may include a spacer characterized by a first surface with which the gas box is coupled, and the
5 spacer may define a recessed ledge on an interior portion of the first surface. The chamber may include a support bracket seated on the recessed ledge that extends along a second surface of the spacer. The chamber may also include a gas distribution plate seated on the support bracket.

[0006] Exemplary chambers may also include an annular liner contacting the gas distribution plate and extending about a surface of the support bracket. The chambers may include a top
10 plate seated on the annular liner and positioned proximate a surface of the gas box. In embodiments, the gas distribution plate, the annular liner, and the top plate may be or include quartz, a ceramic, or coated aluminum. The support bracket and the spacer may at least partially comprise hard anodized aluminum or coated aluminum. Chambers may also include a pedestal configured to support a semiconductor substrate, and the pedestal may include a ceramic heater
15 configured to heat the semiconductor substrate to between about 300 °C and 500 °C.

[0007] In embodiments, a delivery tube may couple the semiconductor processing chamber at the gas box access with a remote plasma source, and the delivery tube may include a quartz interior surface. The quartz interior surface may include a quartz liner disposed within an aluminum delivery tube. The delivery tube may also include an adaptor coupling the delivery
20 tube with a remote plasma source unit, and the adaptor may include a shim proximate the delivery tube.

[0008] The present technology may also include a semiconductor processing system that may include a remote plasma source as well as a delivery tube coupled with the remote plasma source. The system may include a semiconductor processing chamber that may include a gas
25 box defining an access to the semiconductor processing chamber. In embodiments, the access may be centrally located within the gas box, and the delivery tube may be coupled with the gas box at the access. The chamber may also include a spacer characterized by a first surface with which the gas box is coupled, and the spacer may define a recessed ledge on an interior portion of the first surface. The chamber may include a support bracket seated on the recessed ledge and
30 extending along a second surface of the spacer. A portion of the gas box may at least partially

extend parallel to the second surface of the spacer, and the support bracket may be at least partially positioned between the second surface of the spacer and the portion of the gas box at least partially extending parallel to the second surface of the spacer. The chamber may also include a gas distribution plate seated on the support bracket.

5 **[0009]** The system may also include within the chamber an annular liner contacting the gas distribution plate and extending about an interior surface of the support bracket. The chamber may include a top plate seated on the annular liner and positioned proximate a surface of the gas box. The portion of the gas box may include a surface of a recessed portion of the gas box, and the recessed portion of the gas box may be positioned adjacent a portion of the support bracket
10 extending along the second surface of the spacer. In embodiments, the gas distribution plate, the annular liner, and the top plate may be or include quartz, a ceramic, or coated aluminum.

[0010] In embodiments, the top plate may extend within an outer diameter of the access defined by the gas box and may contact the delivery tube or an adaptor positioned at an outlet of the delivery tube. The support bracket and the spacer may at least partially be or include hard
15 anodized aluminum or coated aluminum. The chamber may also include a pedestal configured to support a semiconductor substrate, and the pedestal may include or be a ceramic heater configured to heat the semiconductor substrate to between about 300 °C and 500 °C. In
embodiments, the delivery tube may be or include a quartz interior surface. Additionally, the gas distribution plate may include one or more rings of apertures extending radially outward from a
20 central axis of the gas distribution plate.

[0011] The present technology may also include a method of etching a substrate in a semiconductor processing chamber. The method may include delivering a chlorine-containing precursor to a remote plasma source while generating a plasma to produce plasma effluents. The method may include flowing the plasma effluents through a quartz gas distribution plate in the
25 semiconductor processing chamber. The method may also include etching the substrate at a temperature between about 300 °C and about 500 °C.

[0012] The present technology may also include a semiconductor processing system having a remote plasma source. The system may include a delivery tube coupled with the remote plasma source. The system may also include a semiconductor processing chamber, and the
30 semiconductor processing chamber may include a gas box coupled about a distal region of the

delivery tube. The chamber may include a first annular support contacting the gas box at a first surface of the first annular support, and the first annular support and the gas box together may define a first channel about an interior region of the semiconductor processing chamber. The chamber may also include a gas distribution plate seated within the first channel.

5 **[0013]** The processing chamber may also include an annular liner seated on the gas distribution plate. The chamber may include a top plate seated on the annular liner, and the annular liner and the top plate may be both at least partially seated within the first channel. The chamber may include a second annular support contacting the first annular support at a second surface of the first annular support opposite the first surface of the first annular support. The second annular
10 support and the first annular support together may define a second channel about an interior region of the semiconductor processing chamber. The chamber may also include a second gas distribution plate seated within the second channel. In embodiments, the first gas distribution plate and the second gas distribution plate may each be one of or include quartz, a ceramic, or coated aluminum.

15 **[0014]** The processing chamber may also include at least one pin removably coupling the gas distribution plate with the first annular support. The delivery tube may define at least a portion of a channel between the remote plasma unit and the gas box configured to allow precursor delivery through the delivery tube into the semiconductor processing chamber that bypasses the remote plasma source. The chamber may also include an insert positioned within the delivery
20 tube, and the insert may provide access to a mixing region of the insert from the remote plasma source and the at least a portion of a channel of the delivery tube. In embodiments, the mixing region of the insert may include a first mixing section characterized by a tapered shape from the access to the mixing region of the insert, and the mixing region of the insert may include a second mixing section characterized by an expanding internal diameter from a position
25 proximate the first mixing section to an outlet of the delivery tube.

[0015] In embodiments, the mixing region of the insert further may include a third mixing section characterized by a cylindrical shape having an internal diameter that is less than half the internal diameter of the delivery tube. Additionally, the gas box may include a first gas box plate and a second gas box plate coupled with one another. The second gas box plate may at least
30 partially contact the first annular support along a second surface of the second gas box plate

opposite a first surface of the second gas box plate contacting the first gas box plate. Also, the second gas box plate may define a plurality of channels, and the coupled first gas box plate and second gas box plate may define a flow path through the plurality of channels. In embodiments, the first gas box plate may define a port providing access to a channel of the plurality of channels. The second gas box plate may define at least one entry channel providing access from the plurality of channels to an interior region of the semiconductor processing chamber, and the at least one entry channel may be positioned radially outward from the port defined by the first gas box plate.

[0016] The present technology may also include a semiconductor processing chamber having a gas box providing access to the semiconductor processing chamber. The chamber may include a first annular support contacting the gas box at a first surface of the first annular support, and the first annular support and the gas box may each define a portion of a first channel located at the interface of the gas box and the first annular support. The chamber may include a first gas distribution plate seated within the first channel. Additionally, the chamber may include a second annular support contacting the first annular support at a second surface of the first annular support opposite the first surface of the first annular support. The second annular support may at least partially define a second channel located about an interior region of the semiconductor processing chamber. The chamber may also include a second gas distribution plate seated within the second channel, and the first gas distribution plate and the second gas distribution plate may be or include quartz in embodiments.

[0017] The processing chamber may also include an annular liner seated on the first gas distribution plate. The chamber may include a top plate seated on the annular liner, and the annular liner and the top plate may both at least partially be seated within the first channel. In embodiments, the first gas distribution plate and the second gas distribution plate may be characterized by a similar shape and may each define a plurality of apertures located in rings about the gas distribution plate. Additionally, the gas box may include a first gas box plate and a second gas box plate coupled with one another. The second gas box plate may at least partially contact the first annular support along a second surface of the second gas box plate opposite a first surface of the second gas box plate contacting the first gas box plate. The second gas box plate may define a plurality of channels, and the coupled first gas box plate and second gas box

plate may define a flow path through the plurality of channels. In embodiments, the first gas box plate may define a port providing access to a channel of the plurality of channels. Additionally, the second gas box plate may define at least one entry channel providing access from the plurality of channels to an interior region of the semiconductor processing chamber. In
5 embodiments, the at least one entry channel may be positioned radially outward from the port defined by the first gas box plate.

[0018] Such technology may provide numerous benefits over conventional techniques. For example, the technology may allow improved protection of chamber components that may otherwise be affected by plasma precursors. Additionally, the technology may allow improved
10 component replacement and access based on the chamber design. These and other embodiments, along with many of their advantages and features, are described in more detail in conjunction with the below description and attached figures.

BRIEF DESCRIPTION OF THE DRAWINGS

[0019] A further understanding of the nature and advantages of the disclosed embodiments
15 may be realized by reference to the remaining portions of the specification and the drawings.

[0020] FIG. 1 shows a top plan view of one embodiment of an exemplary processing system.

[0021] FIG. 2 shows a schematic cross-sectional view of an exemplary processing system according to embodiments of the present technology.

[0022] FIG. 3 shows a schematic cross-sectional view of a portion of an exemplary processing
20 chamber according to embodiments of the present technology.

[0023] FIG. 4 shows a schematic cross-sectional view of a delivery system for an exemplary processing chamber according to embodiments of the present technology.

[0024] FIG. 5A shows a top plan view of an exemplary gas distribution plate according to embodiments of the present technology.

[0025] FIG. 5B shows a top plan view of an exemplary gas distribution plate according to
25 embodiments of the present technology.

[0026] FIG. 6 shows a partial schematic cross-sectional view of a portion of an exemplary processing chamber according to embodiments of the present technology.

[0027] FIG. 7 shows a cross-sectional plan view of an exemplary gas distribution plate according to embodiments of the present technology.

[0028] FIG. 8 shows a schematic cross-sectional view of a portion of an exemplary processing chamber according to embodiments of the present technology.

5 [0029] FIG. 9 shows a cross-sectional plan view of an exemplary gas box arrangement according to embodiments of the present technology.

[0030] FIG. 10 shows a cross-sectional view of a portion of an exemplary gas box arrangement according to embodiments of the present technology.

10 [0031] FIG. 11 illustrates a method of etching a substrate according to embodiments of the present technology.

[0032] In the appended figures, similar components and/or features may have the same numerical reference label. Further, various components of the same type may be distinguished by following the reference label by a letter that distinguishes among the similar components and/or features. If only the first numerical reference label is used in the specification, the
15 description is applicable to any one of the similar components and/or features having the same first numerical reference label irrespective of the letter suffix.

DETAILED DESCRIPTION

[0033] In semiconductor processing, etching may be performed for a number of reasons. In dry etching, precursors may be flowed through plasma to produce radical plasma effluents for
20 etching various semiconductor materials. These precursors may include one or more corrosive elements including fluorine, chlorine, or any other chemical element. These elements are exposed not only to the substrate or materials to be etched, but also to the chamber components in which the processing is performed. As a result, exposed surfaces of the chamber may be etched, sputtered, or otherwise degraded by the plasma or the effluents produced by the plasma.
25 The extent of the degradation may be related to the reactivity between the chamber components and the precursors used for the etching.

[0034] Conventional technologies have often dealt with this degradation by providing replaceable components within the chamber. Accordingly, when coatings or components

themselves are degraded, the component may be removed and replaced with a new component that will in turn degrade over time. Not only does this degradation and replacement cost processing time and money, but the degradation itself can impact the processes being performed. For example, as components or coatings are being degraded, particles from the components and coatings affected may be deposited on the substrate being worked. This can cause problems with production including short-circuiting of components as well as uneven processing.

[0035] Many semiconductor chamber components may be made of aluminum. When chlorine-based precursors are used in processing, the chlorine, as well as chlorine radicals, are corrosive and can quickly damage exposed aluminum chamber components. One mechanism for reducing this corrosion is to coat exposed aluminum pieces. However, coating any exposed material can be expensive, imperfect, and can introduce fouling as the material degrades over time. Hence, the more material being coated, the higher may be the chance of having issues with the coating.

[0036] The present technology utilizes alternative components within the chamber to reduce the impact of etchants on the chamber. By removing the plasma generation from the chamber in embodiments, bombardment damage to chamber components can also be reduced. Although the disclosure will routinely identify specific etching processes utilizing the disclosed technology, it will be readily understood that the systems and methods are equally applicable to deposition and cleaning processes as may occur in the described chambers. As such, the technology should not be considered to be so limited as for use with etching processes alone.

[0037] FIG. 1 shows a top plan view of one embodiment of a processing system 100 of deposition, etching, baking, and curing chambers according to disclosed embodiments. In the figure, a pair of front opening unified pods (FOUPs) 102 supply substrates of a variety of sizes that are received by robotic arms 104 and placed into a low pressure holding area 106 before being placed into one of the substrate processing chambers 108a-f, positioned in tandem sections 109a-c. A second robotic arm 110 may be used to transport the substrate wafers from the holding area 106 to the substrate processing chambers 108a-f and back. Each substrate processing chamber 108a-f, can be outfitted to perform a number of substrate processing operations including the etch processes described herein in addition to cyclical layer deposition (CLD), atomic layer deposition (ALD), chemical vapor deposition (CVD), physical vapor deposition (PVD), etch, pre-clean, degas, orientation, and other substrate processes.

[0038] The substrate processing chambers 108a-f may include one or more system components for depositing, annealing, curing and/or etching a dielectric film on the substrate wafer. In one configuration, two pairs of the processing chamber, e.g., 108c-d and 108e-f, may be used to deposit dielectric material on the substrate, and the third pair of processing chambers, e.g., 108a-b, may be used to etch the deposited dielectric. In another configuration, all three pairs of chambers, e.g., 108a-f, may be configured to etch a material on the substrate. Any one or more of the processes described below may be carried out in chamber(s) separated from the fabrication system shown in different embodiments. It will be appreciated that additional configurations of deposition, etching, annealing, and curing chambers for dielectric films are contemplated by system 100. Any of the chambers described below may be utilized in the processing system 100, and may be included as tandem chambers, which may include two similar chambers sharing precursor, environmental, or control features.

[0039] FIG. 2 shows a schematic cross-sectional view of an exemplary processing system 200 according to embodiments of the present technology. The system may include a processing chamber 205, and a remote plasma source ("RPS") unit 210. The RPS unit 210 may be stabilized on a platform 212 having support members 214 that may couple with the processing chamber 205 at one or more positions about the processing chamber 205. By utilizing additional support members 214 along with platform 212, the weight of the RPS unit 210 may be properly distributed to protect components from sheer or other stresses related to the weight of the RPS unit 210. A delivery tube 216 may be coupled between or with the RPS unit 210 and the processing chamber 205 for delivering one or more precursors to the processing chamber 205. A flange adaptor 218 may be positioned about the delivery tube 216 in order to provide additional stability and support against the RPS unit 210, which may otherwise damage the delivery tube 216 from the support weight. The flange adaptor 218 may contact the platform 212 to provide support for the RPS unit 210, additionally so that the weight of the RPS unit 210 is not borne on the delivery tube 216.

[0040] The processing chamber 205 may include a gas box 220 providing access to the processing chamber 205. The gas box 220 may define an access to the processing chamber 205, and in embodiments, the access may be centrally defined or located within the gas box 220. The delivery tube 216 may be positioned or coupled within the access of the gas box 220 providing a

precursor path between the RPS unit 210 and the interior of the processing chamber 205. The flange adaptor 218 may also contact the top plate 220 to distribute at least a portion of the weight of the RPS unit 210, to prevent or reduce stress on the delivery tube 216.

[0041] In embodiments a spacer 222 may at least partially define the processing chamber 205 exterior and interior walls. A gas distribution assembly 225 may be positioned within the processing chamber 205 proximate the delivery tube 216, and the gas distribution assembly 225 may allow distribution of precursors or plasma effluents into the processing chamber 205. A pumping liner 230 may be positioned within a processing region of the processing chamber 205. The pumping liner 230 may allow unreacted precursors or plasma effluents to be exhausted from the processing chamber 205. The pumping liner 230 may additionally allow particles etched in an etching process to be removed from the processing chamber 205 to prevent the particles from remaining on the substrate during subsequent processing operations.

[0042] A pedestal 235 may be included in the processing region of the processing chamber 205 and may be configured to support a substrate during etching or other process operations. The pedestal 235 may have one or more chucking mechanisms in various embodiments including electrostatic, vacuum, or gravitational, for example. The pedestal 235 may be rotatable or translatable in embodiments, and may be raised towards or lowered from the gas distribution assembly 225. In embodiments the pedestal 235 may include one or more lift pins for aiding transfer of a substrate into and out of the processing chamber 205. Pedestal 235 may additionally include heating or cooling mechanisms for maintaining substrate temperatures during processing operations.

[0043] The pedestal 235 may include an inlaid heating element including a filament, or may include one or more tubes or channels configured to pass a temperature controlled fluid that may raise or lower the temperature accordingly. Pedestal 235 may include a platform for supporting a substrate that is or includes a ceramic heater. The ceramic heater may heat the substrate to particular operating temperatures including from about 20 °C to over 1000 °C in embodiments. The ceramic heater may additionally heat the substrate above about 50 °C, above about 100 °C, above about 150 °C, above about 200 °C, above about 250 °C, above about 300 °C, above about 350 °C, above about 400 °C, above about 500 °C, or higher in embodiments. The ceramic heater may additionally maintain the substrate temperature below about 1000 °C, below about 900 °C,

below about 800 °C, below about 700 °C, below about 600 °C, or below about 500 °C in embodiments. The ceramic heater may additionally be configured to heat or maintain the substrate temperature between about 100 °C and about 500 °C in embodiments, or between about 300 °C and about 500 °C in embodiments. In embodiments the heater is configured to maintain the substrate temperature below about 300 °C, in which case alternative metal heating elements may be used instead of a ceramic heater. For example, a coated aluminum heater may be used, or an embedded or coated heater on an aluminum or treated aluminum pedestal.

[0044] The components of processing chamber 205 may be configured to withstand the operating environment during etching or other processing operations. The components of processing chamber 205 may be an anodized or oxidized material, including hard anodized aluminum, for example. Each component within processing chamber 205 that may be contacted by plasma effluents or other corrosive materials may be treated or coated to protect against corrosion. Alternative materials may also be utilized to protect against corrosion from plasma effluents including fluorine or chlorine in embodiments. For example, one or more components within processing chamber 205 may be ceramic or quartz in embodiments. As a particular example, one or more components of gas distribution assembly 225, spacer 222, pumping liner 230, or any component that may be contacted by plasma or non-plasma precursors may be or include quartz or ceramic. Additionally, delivery tube 216 may be or include quartz, such as including a quartz liner within the delivery tube 216. The delivery tube may be aluminum or hard anodized aluminum in embodiments, and may be characterized by a quartz interior surface. RPS unit 210 may also be lined with quartz in order to protect the internal components from corrosion caused by precursors dissociated within the RPS unit 210 including or chlorine, for example. The RPS unit 210 may include anodized metals, and the RPS unit 210 chamber cavities may be lined with quartz to further protect against corrosion.

[0045] By utilizing a remote plasma from RPS unit 210, the processing chamber 205 may be further protected against internal corrosion caused by plasma generation. In embodiments, processing chamber 205 may not be configured to produce a plasma, and plasma generation may be performed externally to the processing chamber 205 in RPS unit 210. In embodiments additional plasma processing may be performed within processing chamber 205, such as by a capacitively-coupled plasma, although other plasma sources may be used. For example, gas box

220 and one or more components of the gas distribution assembly 225 may be utilized as electrodes by which a capacitively-coupled plasma may be produced. Additional or alternative plasma components within the chamber may be used to assist with recombination of plasma effluents by reducing the path length from plasma generation to interaction with a substrate.

5 **[0046]** Precursors dissociated by plasma will recombine after a certain residence time. For example, after a chlorine-based precursor is dissociated within RPS unit 210, the precursor or plasma effluents may be flowed through delivery tube 216 into processing chamber 205, and then interact with a substrate on pedestal 235. Depending on the length of the path of travel for the radical effluents, the effluents or radicals may recombine and at least partially lose the
10 reactivity of the radical precursor. Additionally, the more complicated the path of travel, such as through various tubes or channels, the more protection may be included in the system as each component in contact with the plasma effluents may be treated or coated to protect from corrosion. Accordingly, processing chamber 205 may include a relatively straight line of travel from RPS unit 210 into processing chamber 205, and then through exhaust plenum 230.
15 Additionally, once within processing chamber 205, precursors or plasma effluents may travel through one or more inline aspects of the gas distribution assembly 225 to contact a substrate. Components of the gas distribution assembly 225 may be utilized to improve uniformity of flow towards a substrate, but otherwise maintain a reduced length of precursor flow path to reduce recombination of the plasma effluents as well as residence time within the processing chamber
20 205.

[0047] Turning to **FIG. 3** is shown a schematic cross-sectional view of a portion of an exemplary processing chamber 205 according to embodiments of the present technology. FIG. 3 includes a partial view of components of gas distribution assembly 225 of FIG. 2, and may include similar components as previously described. Processing chamber 205 as illustrated in
25 FIG. 3 may include delivery tube 216, flange adaptor 218, gas box 220, and spacer 222, for example. As shown with additional detail, spacer 222 may be characterized by a first surface 321 with which the gas box 220 is coupled. Spacer 222 may define a recessed ledge 323 on an interior portion of the first surface 321 in embodiments. An interior portion may be a portion located radially towards a central axis of the processing chamber 205 relative to the component
30 or relative to the chamber, for example, or may be a portion facing the interior of the processing

chamber 205. As illustrated in the figure, recessed ledge 323 may be formed on the side of the first surface 321 of spacer 222 towards the interior of the processing chamber 205, and may be located proximate the coupling location of gas box 220. Gas box 220 may at least partially cover recessed ledge 323 in embodiments, and may completely cover recessed ledge 323.

- 5 **[0048]** A support bracket 305 may be seated on the recessed ledge 323 of spacer 222. The support bracket 305 may extend along a second surface 324 of the spacer 222. The second surface 324 of spacer 222 may face the interior of processing chamber 205, and be a surface of spacer 222 adjacent first surface 321 in embodiments. Support bracket 305 may extend at about or essentially a right angle from recessed ledge 323 along second surface 324 of spacer 222.
- 10 Support bracket 305 may be characterized by an S or Z-shape depending on orientation to provide support ledge 307 extending from support bracket 305 into processing chamber 205. Support bracket 305 may have an annular shape and extend about the interior of processing chamber 205. A gasket or o-ring 309 may be positioned adjacent support bracket 305, and may be radially outward from support bracket 305 in the processing chamber 205 configuration.
- 15 Gasket 309 may be positioned between gas box 220 and spacer 222 to provide a fluid seal about the components and support bracket 305. When gas box 220 is coupled with spacer 222, gasket or o-ring 309 may be compressed to form a seal between the components.

- [0049]** As further illustrated, a portion of the gas box 220 may also extend beyond the first surface 321 of the spacer 222 to which the gas box 220 is coupled, and may at least partially
- 20 extend parallel to the second surface 324 of the spacer 222, or the support bracket 305. As shown, a portion of the gas box 220 crosses a plane of the first surface 321 of the spacer 222 extending within the processing chamber 205 parallel to the second surface 324 of the spacer 222. The portion of the gas box 220 may be a recessed portion of the gas box 220 within the processing chamber 205, and the recessed portion of the gas box 220 may be positioned adjacent
- 25 a portion of the support bracket 305 extending along the second surface 324 of the spacer 222. In embodiments the gas box 220 may not extend perfectly parallel, and may extend at an angle towards or away from the second surface 324 of the spacer 222 as well. The support bracket 305 may be at least partially positioned between the second surface 324 of the spacer 222 and a portion of the gas box 220 that is at least partially extending parallel to the second surface 324 of
- 30 the spacer 222. The support bracket 305 may be spaced between the spacer 222 and gas box 220

in embodiments, or may be directly contacting one or both of the second surface 324 of the spacer 220, or the portion of the gas box 220 that is at least partially extending parallel to the second surface 324 of the spacer 220.

[0050] Seated on support bracket 305 may be a gas distribution plate 310 that is configured to provide a uniform flow of precursor or plasma effluent into the processing region of the processing chamber 205 for interaction with the substrate. In embodiments, gas distribution plate 310 may be seated on support bracket 305 without additional coupling material, and may seat directly on support ledge 307. An annular liner 312 may be seated or positioned on gas distribution plate 310 and may extend about the interior of processing chamber 205 to cover an otherwise exposed region or interior surface of support bracket 305.

[0051] A top plate 314 may be positioned or seated on the annular liner 312, and positioned proximate a surface of the gas box facing the interior of processing chamber 205. The top plate 314 may extend about an outlet from delivery tube 216 and may directly contact the outlet from delivery tube 216 to reduce or prevent precursor or plasma effluent flow from contacting the surface of gas box 220 facing the interior of the chamber. Additionally, the top plate 314 may extend past or within an outer diameter of the access defined by the gas box 220, and may or may not directly contact the delivery tube 216 or an adaptor positioned at an outlet of the delivery tube 216. In embodiments a gap may be present between the top plate 314 and the gas box 220, or the top plate 314 may be flush and directly contacting the gas box 220. In embodiments the gap may be less than 5 cm, and may be equal to or less than about 4 cm, 3 cm, 2 cm, 1 cm, 0.5 cm, 0.1 cm, or 0 cm in which case the top plate 314 is directly contacting the gas box 220. The top plate 314 may be a flat plate defining an aperture at a location at which delivery tube 216 contacts or meets the top plate 314. The top plate 314 may otherwise be a solid design to protect gas box 220 from exposure to precursors or plasma effluents.

[0052] One or more of gas distribution plate 310, annular liner 312, and top plate 314 may compose the gas distribution assembly 225 of FIG. 2. Each of these components may be coated or designed to be inert or have reduced impact from plasma effluents and precursors. For example, gas distribution plate 310, annular liner 312, and top plate 314 may each be made from or include quartz in embodiments, or may be made or coated with material that is unreactive or has reduced reactivity to corrosive materials including fluorine or chlorine. For example, any of

the gas distribution plate 310, annular liner 312, or top plate 314 may be ceramic, or may be coated or anodized aluminum. While gas distribution plate 310 may uniformly disperse precursors or plasma effluents from delivery tube 216 into the processing region of processing chamber 205, annular liner 312 and top plate 314 may be used to protect additional components within the processing chamber. For example, as precursors or plasma effluents are distributed from delivery tube 216, the precursors may flow radially outward within gas distribution assembly 225 and at least partially fill the cavity of gas distribution assembly 225 defined between gas distribution plate 310, annular liner 312, and top plate 314. Annular liner 312 and top plate 314 may prevent the reactive precursors or plasma effluents from contacting gas box 220 and support bracket 312 before being distributed or flowed through gas distribution plate 310.

[0053] Once precursors distribute through the gas distribution plate 310, the flow may at least partially contact support bracket 305 or spacer 222. This contacting may be minimized based on a pressurized or vacuum flow through the chamber. Accordingly, a region of the processing chamber 205 between the delivery tube 216 and the gas distribution plate 310 may be a location where residence time within the chamber of the precursors is longer than after the precursors have flowed through the gas distribution plate 310. By covering the otherwise exposed portions of the processing chamber 205 including the interior facing surfaces of the support bracket 305 and gas box 310 with, respectively, the annular liner 312 and top plate 314. Chamber component lifetime may be improved, which may reduce replacement costs over the lifetime of the processing chamber 205. At least portions of the spacer 222 and support bracket 305 may be aluminum and may be contacted by the precursors or plasma effluents after distribution or flow through the gas distribution plate 310. The spacer 222 and support bracket 305, or at least the exposed surfaces of these components, thus may be coated or be composed of materials such as hard anodized aluminum to reduce their degradation. Additionally these materials may also be composed of or include quartz, ceramics, or other non or less reactive materials.

[0054] FIG. 4 illustrates a schematic cross-sectional view of a delivery system 400 for an exemplary processing chamber according to embodiments of the present technology. FIG. 4 may include components as previously illustrated in FIGS. 2 and 3, and may include RPS unit 210, platform 212, delivery tube 216, flange adaptor 218, gas box 220, and top plate 314, for

example. As illustrated, the delivery tube 216 may couple the processing chamber 205 at the access defined by the gas box 220 with RPS unit 210. Because of the exposure to plasma effluents that may be corrosive, delivery tube 216 may be composed of or include a coated or protected material, such as hard anodized aluminum, or a coated aluminum. In embodiments, delivery tube 216 may also include a liner, such as a quartz liner, along the interior of the delivery tube 216 that may be exposed to plasma effluents.

[0055] One or more gaskets or o-rings 405a-c may be included between components such as the RPS unit 210 and the platform 212, platform 212 and flange adaptor 218, as well as flange adaptor 218 and gas box 220. An adaptor 410 may be included coupling the delivery tube 216 with the RPS unit 210 in embodiments. The adaptor 410 may be at least partially quartz, and may include a flange or shim. The flange or shim of adaptor 410 may allow an improved seal between the RPS unit 210 and the delivery tube 216 to protect components including o-ring or gasket 405a from being contacted by plasma effluents, which may corrode the o-ring or gasket 405a, RPS unit 210, or platform 212. The flange or shim may be a foil o-ring in embodiments or another material providing a seal between the components, and that may also be inert to or protected from corrosion by precursors or plasma effluents, such as with a coating, protective layer, or material selection. Delivery tube 216 may also include an adaptor 415 coupled with an outlet of the delivery tube 216. The adaptor 415 may be coupled with the gas box 220 or top plate 314 in embodiments. In embodiments the adaptor 415 may be an adaptation of the top plate 314 that may be shaped, tapered, flanged, or otherwise adjusted to reduce or prevent exposure of the gas box 220 to precursors or plasma effluents being delivered through delivery tube 216.

[0056] FIGS. 5A-5B illustrate exemplary structures for the gas distribution plate 310 according to embodiments of the present technology. As illustrated in FIG. 5A, gas distribution plate 310a may include one or more rings of apertures extending radially outward from a central axis of the gas distribution plate 310a. The rings may include any number of apertures that may be grouped or spaced to adjust the amount of flow through the gas distribution plate 310a. As illustrated, the gas distribution plate 310a includes four rings of apertures with each radially outward ring including apertures characterized by a larger diameter than more internal rings. In embodiments adjustments can be made both to the number of rings as well as the size and shape

of the apertures. For example, the gas distribution plate may have 2, 3, 4, 5, 6, 7, 8, 9, 10, or more rings extending radially outward from the central axis of the gas distribution plate 310a. Additionally, the number of apertures included in each ring as well as the spacing between each aperture within a ring may be adjusted. For example, each ring may have less than or about 3, 4, 5, 6, 8, 10, 15, 20, 25, 30, 35, 40, 45, 50, 60, 70, 80, 90, or more apertures per ring. Additionally, the spacing between each aperture may be similar or different from one aperture to the next within a ring, as well as between rings. Such adjustments can be used to optimize flow through the gas distribution plate 310a.

[0057] FIG. 5B illustrates a gas distribution plate 310b having a plurality of rings of equally sized apertures. As illustrated, one or more of the rings may be rotated or offset from an adjacent ring. Such a design may provide a more uniform flow through the gas distribution plate 310b. The apertures may have similar or different sizes throughout the gas distribution plate either within a particular ring or across rings. Additionally, the spacing between apertures may be uniform or different within a ring or between rings. For example, an exemplary gas distribution plate 310b may include a plurality of rings having uniform aperture sizes between about 0.1 mm and about 10 mm. The aperture sizes may be between about 1 mm and about 5 mm, or between about 2 mm and about 4 mm in embodiments. Additionally, each ring may have between about 3 and about 100 apertures or more. For example, rings toward the interior of the gas distribution plate 310b may include fewer apertures, while rings radially outward from the center of the gas distribution plate 310b may include more apertures. Accordingly, any smaller range of apertures within a ring is specifically included by the larger range. It is to be understood that FIGS. 5A and 5B are merely examples of gas distribution plate 210 designs and configurations, and any number of modifications to aperture location, size, and shape are additionally encompassed by the present technology.

[0058] Turning to FIG. 6 is shown a schematic cross-sectional view of a portion of an exemplary processing system 600 according to embodiments of the present technology. The processing system 600 may include certain similar components as the system illustrated in FIG. 2, for example. The processing system 600 may include a remote plasma source (“RPS”) unit 610 positioned on a platform 612 with support members 614. The RPS unit 610, platform 612, and support members 614 may be similar to those previously described. The processing system

600 may further include a delivery tube 616 supported by an additional flange adaptor 618, and the delivery tube 616 may be coupled with the RPS unit 610. Although the delivery tube 616 and flange adaptor 618 may have similar characteristics to those previously described, the dimensions may differ from those of FIG. 2 based on differences with processing chamber 605.

5 For example, both delivery tube 616 and flange adaptor 618 may have smaller length dimensions than those of the processing system illustrated in FIG. 2. These differences, and their advantages, will be explained in detail below.

[0059] As illustrated in FIGS. 2 and 3, processing chamber 205 may include a hinged design having the support bracket 205 lowered within the processing chamber 205 and positioned on
10 spacer 222. Gas box 220 may then be positioned on top of the components and coupled with the spacer 222. This design may pose difficulties with removing the support bracket 205 for replacement as well as insertion of the support bracket 205 during production of the processing chamber 205. Potentially the support bracket 205, during initial positioning or replacement, may scratch the spacer 222. If the spacer 222 has a coating or an anodized finish, surface defects or
15 scratches may provide locations for corrosion, or earlier corrosion, if contacted by precursors or plasma effluents. Accordingly, processing chamber 605 additionally includes features for ease of production and replacement.

[0060] Processing chamber 605 includes a gas box 620 defining an access to the semiconductor processing chamber 605 for delivery tube 616. The gas box 620 may be coupled
20 about a distal region of the delivery tube 616, or the delivery tube 616 may pass through the gas box 620 in embodiments. Gas box 620 may include a planar or substantially planar surface to which the flange adaptor 618 is coupled. The processing chamber 605 may also include a first annular support 622 contacting the gas box 620 along a surface opposite the planar or substantially planar surface of the gas box 620. The first annular support 622 may contact the
25 gas box 620 at a first surface of the annular support. The first annular support 622 and the gas box 620 together may define at least a portion of a first channel 623 about an interior region of the processing chamber. The first channel 623 may be located at the interface of the gas box and the first annular support. The first annular support 622 may define a recessed ledge at an inner diameter of the first annular support. The gas box 620 may define a recessed ledge within the
30 surface opposite the planar or substantially planar surface of the gas box 620. The recessed

ledge defined by the gas box 620 may be defined to coincide with the location of the recessed ledge of the first annular support 622 to define the first channel 623. A gas distribution assembly 625 may be positioned or seated within the first channel.

[0061] Gas distribution assembly 625 may include a gas distribution plate, annular liner, and top plate as previously described, or may include fewer of the components. For example, gas distribution assembly 625 may be a gas distribution plate seated within the first channel 623. In embodiments, an annular liner may be seated on the gas distribution plate, and a top plate may be seated on the annular liner, and both the annular liner and top plate may be at least partially seated within the first channel 623. The components of the gas distribution assembly 625 may be positioned to protect surfaces of the first channel 623, gas box 620, and first annular support 622 from exposure to precursors or plasma effluents delivered via delivery tube 616. The first channel 623 may have dimensions equivalent to the gas distribution assembly 625 so the gas distribution assembly is flush within the first channel 623. In other embodiments the first channel may have one or more gaps along an exterior diameter of the gas distribution assembly, as well as between the top plate and the gas box 620 as previously described.

[0062] In some embodiments a second annular support 624 may be included and may contact the first annular support 622 at a second surface of the first annular support 622 opposite the first surface of the first annular support 622. The second annular support 624 may have a similar shape as the first annular support 622. In embodiments, the second annular support 624 may have a thickness greater than or less than the first annular support 622. The second annular support 624 may also define a recessed ledge at an inner diameter of the second annular support, similar to the first annular support 622. The recessed ledge of the second annular support 624 along with the second surface of the first annular support 622 may each at least partially define a second channel 626 about an interior region of the semiconductor processing chamber. Although not illustrated, the first annular support 622 may also define a recessed ledge within the second surface of the first annular support similar to the gas box 620. This recessed ledge may increase the height of the second channel 626 to accommodate additional components similar to those of gas distribution assembly 625.

[0063] The processing chamber 605 may also include a second gas distribution plate 627 seated within the second channel 626. Second gas distribution plate 627 and the gas distribution

plate of gas distribution assembly 625 may be similar or different designs, and may both be made of or include quartz or materials as previously described. The gas distribution plates may have similar aperture configurations to one another, or different configurations from one another, and either or both gas distribution plates may include a configuration similar to those discussed with respect to FIGS. 5A-5B. For example, the first gas distribution plate of gas distribution assembly 625 and the second gas distribution plate 627 may be characterized by a similar shape, and may each define a plurality of apertures located in rings about the individual gas distribution plate. In embodiments the plates may have the apertures be aligned or may have the apertures offset from one another to improve uniformity of flow through the plates. Although not illustrated, it is to be understood that the processing chamber 605 may also include a pedestal, heater, and other components as described with relation to FIG. 2.

[0064] The gas box 620, the first annular support 622, and the second annular support 624 may have similar external diameters and be stacked to at least partially define the outer dimensions of the processing chamber 605, as well as at least partially define the dimensions of the interior or processing region of the processing chamber 605. The components may be stacked as illustrated to define the first channel 623 and second channel 626. This stacked design as well as the planar surface of gas box 620 may allow for shorter support members 614, adaptor flange 618, and delivery tube 616. The height of these components may be reduced because the different gas box 620 design may not include the recessed portion extending into the processing chamber 605. As such, the delivery tube 616 may be of a reduced length to access the interior of the processing chamber 605. By reducing the delivery tube length, precursors or plasma effluents delivered to the processing chamber 605 may have a shorter flow path to the substrate. By reducing the length of the flow path, dissociation of plasma precursors may be maintained, and an etching process may be more efficient than when performed in a chamber with a longer flow path from plasma effluent generation to contact with a substrate or material to be etched.

[0065] FIG. 7 illustrates a cross-sectional plan view of an exemplary gas distribution plate 725 according to embodiments of the present technology. The figure shows the coupling of the gas distribution plate 725 to the first annular support 622 as discussed above, along with a perspective from the delivery tube 616. As illustrated, pins 631 are included to support and locate the gas distribution plate 725 to prevent or reduce movement of the plate within the first

channel 623. Unlike being seated on a support bracket such as in FIG. 2, by utilizing the first annular support member 622, a direct connection can be made to ensure proper position or orientation of the gas distribution plate 725. The processing chamber 605 may include at least one pin 631, and may include any number of pins such as pins 631a, 631b, and 631c, for
5 example that may removably couple the gas distribution plate 725 with the first annular support 622.

[0066] The pins may extend through the first annular support 622 in embodiments to additionally pin the second gas distribution plate 627 to the second annular support 624, or may be stopped within the first annular support 622 in embodiments. The pins may merely hold the
10 plates in relative position, or may specifically fix the plates in position such as with a coupling member, such as, e.g. a bolt, screw, etc., that may prevent withdrawal of the component without removal of the coupling member. During production, the gas distribution plate 725 may be slid onto the pins before the gas box 620 is coupled with the first annular support 622. The gas distribution plate 725 may then be prevented or substantially prevented from moving during
15 processing, which may otherwise allow one or more components to become scratched or have a coating or protective layer removed or damaged.

[0067] Turning to FIG. 8 is shown a schematic cross-sectional view of a portion of an exemplary processing chamber 800 according to embodiments of the present technology. Processing chamber 800 may be similar to processing chamber 605 of FIG. 6 with adjustments to
20 the delivery tube 816, adaptor flange 818, and gas box 820. Although several components of the processing system are not shown, other components may be as previously described. As shown, the adaptor flange 818 may define a port 825 and at least a portion of a channel 827 for providing access for a precursor configured to bypass an RPS unit and enter the delivery tube 816 and the processing chamber 805. The delivery tube 816 may also define at least a portion of
25 the channel 827 between the RPS unit and the gas box 820 to allow precursor delivery into the semiconductor processing chamber 820. The delivery tube 816 may also define one or more apertures 828 providing access for precursors or plasma effluents from the RPS unit. In embodiments, the apertures 828 may be spaced about the delivery tube to provide access around the channel 827.

[0068] An insert 829 may be positioned within the delivery tube 816 as illustrated in the figure. The insert 829 may provide access to a mixing region 830 of the insert 829 from the RPS unit and the at least a portion of the channel 827 of the delivery tube 816. The mixing region 830 of the insert 829 may be characterized by multiple mixing sections. A first mixing section 831 may be characterized by a tapered shape from the access to the mixing region 830 of the insert 829. The access to the mixing region may have a diameter up to the inner diameter of the delivery tube 816 in embodiments. The mixing region 830 of insert 829 may also include a second mixing section 833 characterized by an expanding internal diameter from a position proximate the first mixing section 831 to an outlet of the delivery tube 816.

[0069] The mixing region 830 may further include a third mixing section 835 characterized by a cylindrical shape having an internal diameter that is smaller than the internal diameter of the delivery tube 816. For example, the third mixing section 835 may have an internal diameter that is less than or about 90% of the internal diameter of the delivery tube 816. The internal diameter of the third mixing section 835 may also be less than or about 85%, 80%, 75%, 65%, 60%, 55%, 50%, 45%, 40%, 35%, 30%, 25%, 20%, 15%, 10%, or 5% of the internal diameter of the delivery tube 816 in embodiments. The internal diameter of the third mixing section may also be greater than or about 5%, 10%, 15%, 20%, 25%, 30%, 35%, 40%, 45%, 50%, 55%, 60%, 65%, 70%, 75%, 80%, 85%, 90%, or 95% of the internal diameter of the delivery tube 816 in embodiments. By including the mixing sections and the insert, precursors introduced through the channel 827 may be mixed more uniformly with precursors or plasma effluents introduced through the RPS unit before entering the processing chamber 805.

[0070] As illustrated in FIG. 8, gas box 820 may be made of multiple plates to allow further access for bypass precursors that may be maintained separate from any precursors or plasma effluents introduced from the RPS unit until they enter the processing chamber 805. The gas box 820 may include a first gas box plate 840 and a second gas box plate 842 that are coupled with one another in embodiments. The second gas box plate 842 may at least partially contact a first annular support 622 along a second surface of the second gas box plate 842. The second surface of the gas box plate 842 may be opposite a first surface of the second gas box plate 842 that is in contact with the first gas box plate 840. The second gas box plate 842 may define a compound channel or a plurality of channels 845 in embodiments. When the first gas box plate 840 is

coupled with the second gas box plate, a flow path may be defined through the compound channel or plurality of channels 845. The first gas box plate 840 may additionally define a port 847 providing access to at least one channel of the plurality of channels 845. A bypass precursor may be introduced through the port 847 and be flowed into the processing chamber separately from plasma effluents.

[0071] FIG. 9 shows a cross-sectional plan view of an exemplary gas box 820 arrangement according to embodiments of the present technology. As described above, the gas box 820 may include a first gas box plate 840 and a second gas box plate 842 coupled together. The two plates of the gas box 820 define an access for delivery tube 816. A plurality of channels 845, which may be considered a compound channel, are defined within the second gas box plate 842. A port 847 in first gas box plate 840 may provide access to the plurality of channels 845 and a flow path from the port 847 for a precursor that may bypass the RPS unit. The plurality of channels 845 may provide a flow pattern for more uniformly dispersing the precursor introduced through port 847 into processing chamber 805. The plurality of channels 845 may be defined to produce a recursive flow of an introduced bypass precursor from the port 847 throughout the plurality of channels 845.

[0072] The second gas box plate 842 may additionally define at least one channel 949, such as an entry channel, providing access from the plurality of channels 845 to an interior region of the semiconductor processing chamber 805. The second gas box plate 842 may also define a plurality of channels 949 to provide more uniform flow of a precursor into the processing region. Channels 949 defined by the second gas box plate 842 may be positioned or located radially outward from the port 847 defined by the first gas box plate 840 in embodiments. Such a configuration may provide more uniform distribution of the precursor through the channels 845 before entering the processing chamber 805 through the channels 949 in second gas box plate 842.

[0073] FIG. 10 illustrates a cross-sectional view of a portion of an exemplary gas box 820 arrangement according to embodiments of the present technology. Gas box 820 may include a first gas box plate 840 and a second gas box plate 842 as previously described. Second gas box plate 842 may define a plurality of channels 845, as well as one or more entry channels 949 providing access to the processing chamber 805 previously discussed. A precursor may bypass

the RPS unit and enter the processing chamber through entry channels 949 and contact a gas distribution assembly, such as gas distribution assembly 625 previously discussed. Gas distribution assembly 625 may include a top plate 1020, which may include one or more apertures 1025 allowing the bypass precursor to enter the gas distribution assembly 625 and be distributed to a substrate for processing. Additionally, or alternatively, top plate 1020 may not include apertures 1025 in which case the bypass precursor entering the processing chamber 949 may pass around gas distribution assembly 625 to enter a processing region of the processing chamber. A first annular support on which the gas distribution assembly 625 may be seated may define notches by which the bypass precursor may pass the gas distribution assembly 625. The bypass precursor may then be maintained fluidly separate from any precursors or plasma effluents distributed from the RPS unit until after the precursors have passed through the gas distribution assembly 625. The gas distribution assembly 625 may also be positioned flush with a sidewall of the gas box 820 to ensure the bypass precursor enters the gas distribution assembly 625 through apertures 1025 in top plate 1020 in embodiments.

[0074] FIG. 11 illustrates a method 1100 of etching a substrate according to embodiments of the present technology. Method 1100 may include delivering a chlorine-containing precursor to an RPS unit while generating a plasma to produce plasma effluents at operation 1110. At operation 1120, the plasma effluents may be flowed into a processing chamber and through a quartz gas distribution plate. The plasma effluents may etch a substrate housed within the processing chamber at operation 1030. The processing chamber may be any of the chambers discussed in the preceding sections. The etching operation may be conducted at a temperature between about 300 °C and about 500 °C in embodiments and may be below about 300 °C in embodiments.

[0075] The etching process may additionally include introducing one or more precursors that bypass the RPS unit through any of the previously described ports. The chamber may be maintained under vacuum in embodiments, and may also be pressurized to about 1 Torr or greater, such as up to about 3 Torr, up to about 5 Torr, up to about 10 Torr, up to about 20 Torr, or higher. When performing method 1100 in one of the chambers described with relation to the previous figures, the chamber components may be protected from the plasma effluents.

Consequently the chamber components may not degrade as quickly as unprotected components,

and may require less maintenance, less cleaning, and less frequent replacement than some conventional chamber components. Additionally, the chambers described may allow a shorter flow path from the remote plasma unit to the substrate, which may increase the efficiency of etching operations due to less recombination of dissociated chlorine.

5 **[0076]** In the preceding description, for the purposes of explanation, numerous details have been set forth in order to provide an understanding of various embodiments of the present technology. It will be apparent to one skilled in the art, however, that certain embodiments may be practiced without some of these details, or with additional details.

10 **[0077]** Having disclosed several embodiments, it will be recognized by those of skill in the art that various modifications, alternative constructions, and equivalents may be used without departing from the spirit of the embodiments. Additionally, a number of well-known processes and elements have not been described in order to avoid unnecessarily obscuring the present technology. Accordingly, the above description should not be taken as limiting the scope of the technology.

15 **[0078]** Where a range of values is provided, it is understood that each intervening value, to the smallest fraction of the unit of the lower limit, unless the context clearly dictates otherwise, between the upper and lower limits of that range is also specifically disclosed. Any narrower range between any stated values or unstated intervening values in a stated range and any other stated or intervening value in that stated range is encompassed. The upper and lower limits of
20 those smaller ranges may independently be included or excluded in the range, and each range where either, neither, or both limits are included in the smaller ranges is also encompassed within the technology, subject to any specifically excluded limit in the stated range. Where the stated range includes one or both of the limits, ranges excluding either or both of those included limits are also included.

25 **[0079]** As used herein and in the appended claims, the singular forms “a”, “an”, and “the” include plural references unless the context clearly dictates otherwise. Thus, for example, reference to “an aperture” includes a plurality of such apertures, and reference to “the plate” includes reference to one or more plates and equivalents thereof known to those skilled in the art, and so forth.

[0080] Also, the words “comprise(s)”, “comprising”, “contain(s)”, “containing”, “include(s)”, and “including”, when used in this specification and in the following claims, are intended to specify the presence of stated features, integers, components, or operations, but they do not preclude the presence or addition of one or more other features, integers, components, operations, acts, or groups.

5

WHAT IS CLAIMED IS:

1. A semiconductor processing system comprising:
a remote plasma source;
a delivery tube coupled with the remote plasma source;
5 a semiconductor processing chamber, wherein the semiconductor processing chamber comprises:
a gas box defining an access to the semiconductor processing chamber, wherein the access is centrally located within the gas box, and wherein the delivery tube is coupled with the gas box at the access,
10 a spacer characterized by a first surface with which the gas box is coupled, wherein the spacer defines a recessed ledge on an interior portion of the first surface,
a support bracket seated on the recessed ledge and extending along a second surface of the spacer, wherein a portion of the gas box at least partially extends parallel to the second surface of the spacer, and wherein the support bracket is at least
15 partially positioned between the second surface of the spacer and the portion of the gas box at least partially extending parallel to the second surface of the spacer, and
a gas distribution plate seated on the support bracket.
2. The semiconductor processing chamber of claim 1, further comprising an annular liner contacting the gas distribution plate and extending about an interior surface of the
20 support bracket.
3. The semiconductor processing chamber of claim 2, further comprising a top plate seated on the annular liner and positioned proximate a surface of the gas box.
4. The semiconductor processing chamber of claim 3, wherein the portion of the gas box comprises a surface of a recessed portion of the gas box, wherein the recessed
25 portion of the gas box is positioned adjacent a portion of the support bracket extending along the second surface of the spacer.

5. The semiconductor processing chamber of claim 3, wherein the top plate extends within an outer diameter of the access defined by the gas box and contacts the delivery tube or an adaptor positioned at an outlet of the delivery tube.

6. The semiconductor processing chamber of claim 1, further comprising a
5 pedestal configured to support a semiconductor substrate, wherein the pedestal comprises a ceramic heater configured to heat the semiconductor substrate to between about 300 °C and 500 °C.

7. The semiconductor processing chamber of claim 1, wherein the gas
distribution plate comprises one or more rings of apertures extending radially outward from a
10 central axis of the gas distribution plate.

8. A semiconductor processing chamber comprising:
a gas box defining an access to the semiconductor processing chamber;
a spacer characterized by a first surface with which the gas box is coupled,
wherein the spacer defines a recessed ledge on an interior portion of the first surface;
15 a support bracket seated on the recessed ledge and extending along a second
surface of the spacer; and
a gas distribution plate seated on the support bracket.

9. The semiconductor processing chamber of claim 8, further comprising an
annular liner contacting the gas distribution plate and extending about a surface of the support
20 bracket.

10. The semiconductor processing chamber of claim 9, further comprising a
top plate seated on the annular liner and positioned proximate a surface of the gas box.

11. The semiconductor processing chamber of claim 10, wherein the gas
distribution plate, the annular liner, and the top plate comprise quartz, a ceramic, or coated
25 aluminum.

12. The semiconductor processing chamber of claim 8, wherein the support
bracket and the spacer at least partially comprise hard anodized aluminum or coated aluminum.

13. The semiconductor processing chamber of claim 8, further comprising a delivery tube coupling the semiconductor processing chamber at the gas box access with a remote plasma source, wherein the delivery tube comprises a quartz interior surface.

14. The semiconductor processing chamber of claim 13, wherein the quartz
5 interior surface comprises a quartz liner disposed within an aluminum delivery tube.

15. The semiconductor processing chamber of claim 13, wherein the delivery tube further comprises an adaptor coupling the delivery tube with a remote plasma source unit, and wherein the adaptor further comprises a shim proximate the delivery tube.

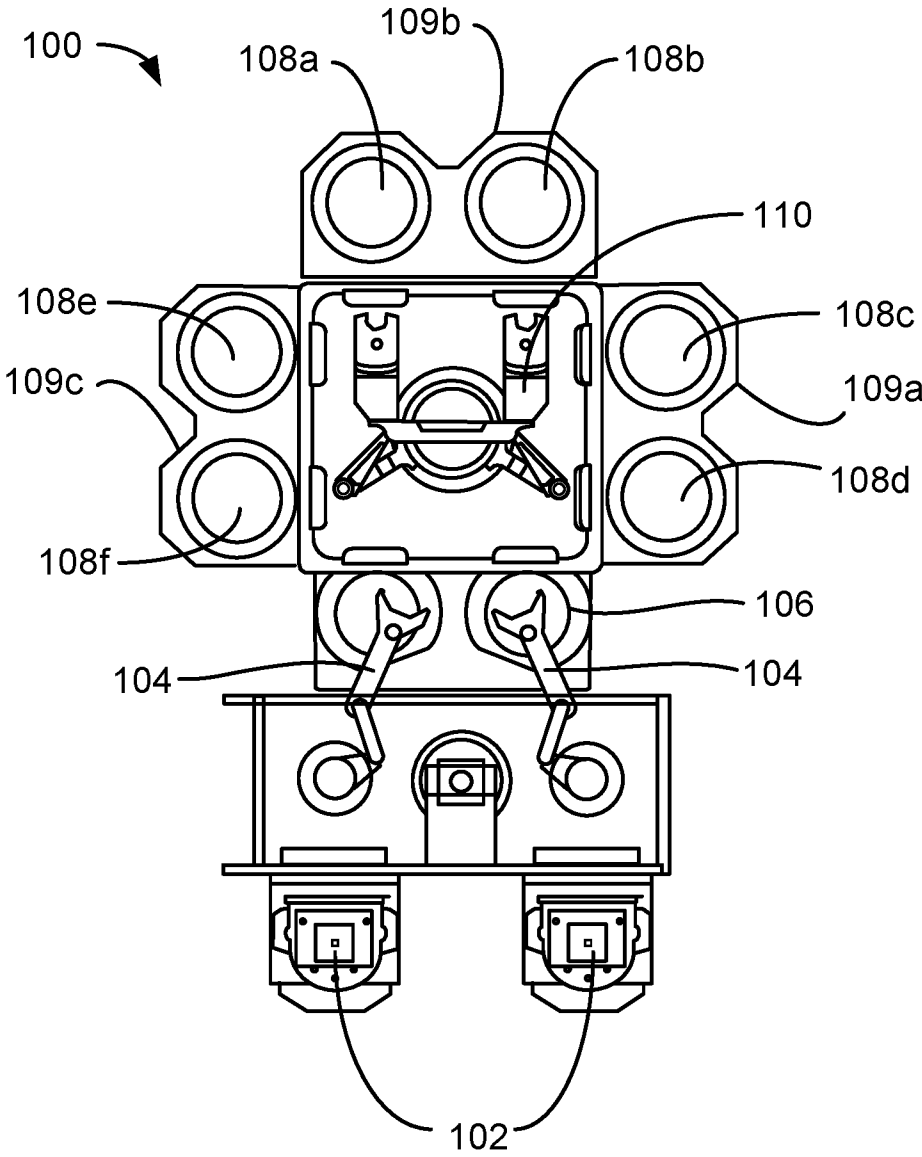


FIG. 1

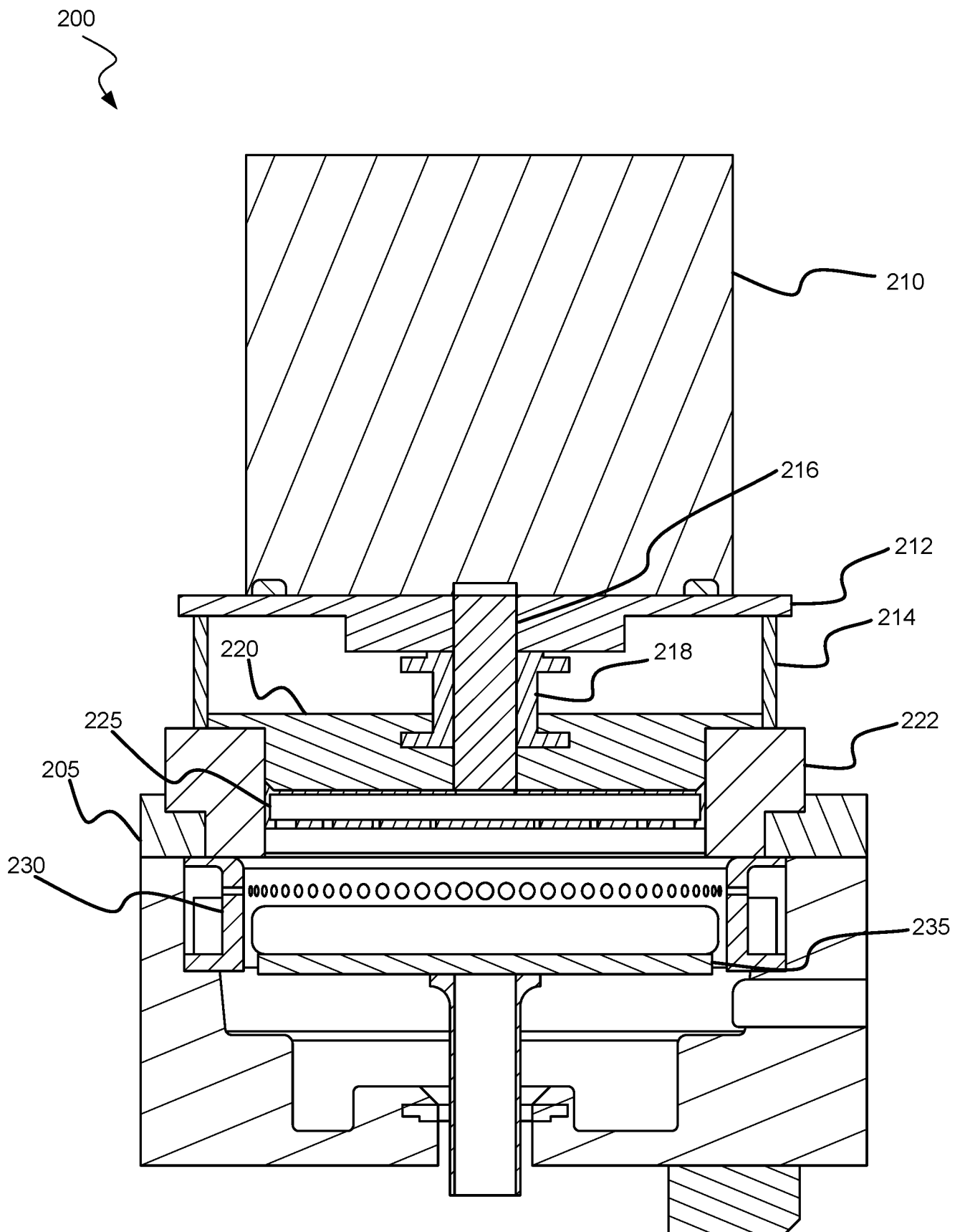


FIG. 2

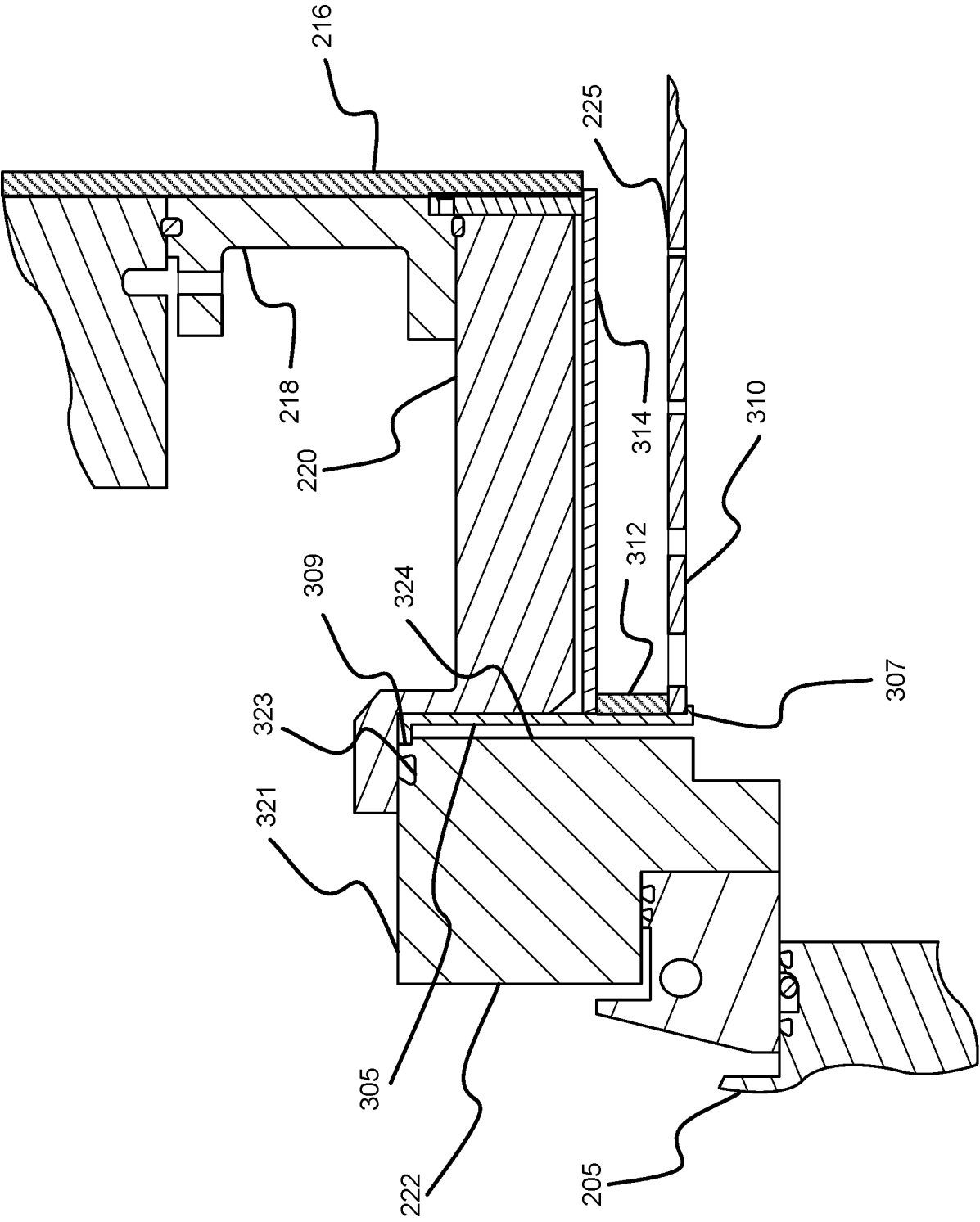


FIG. 3

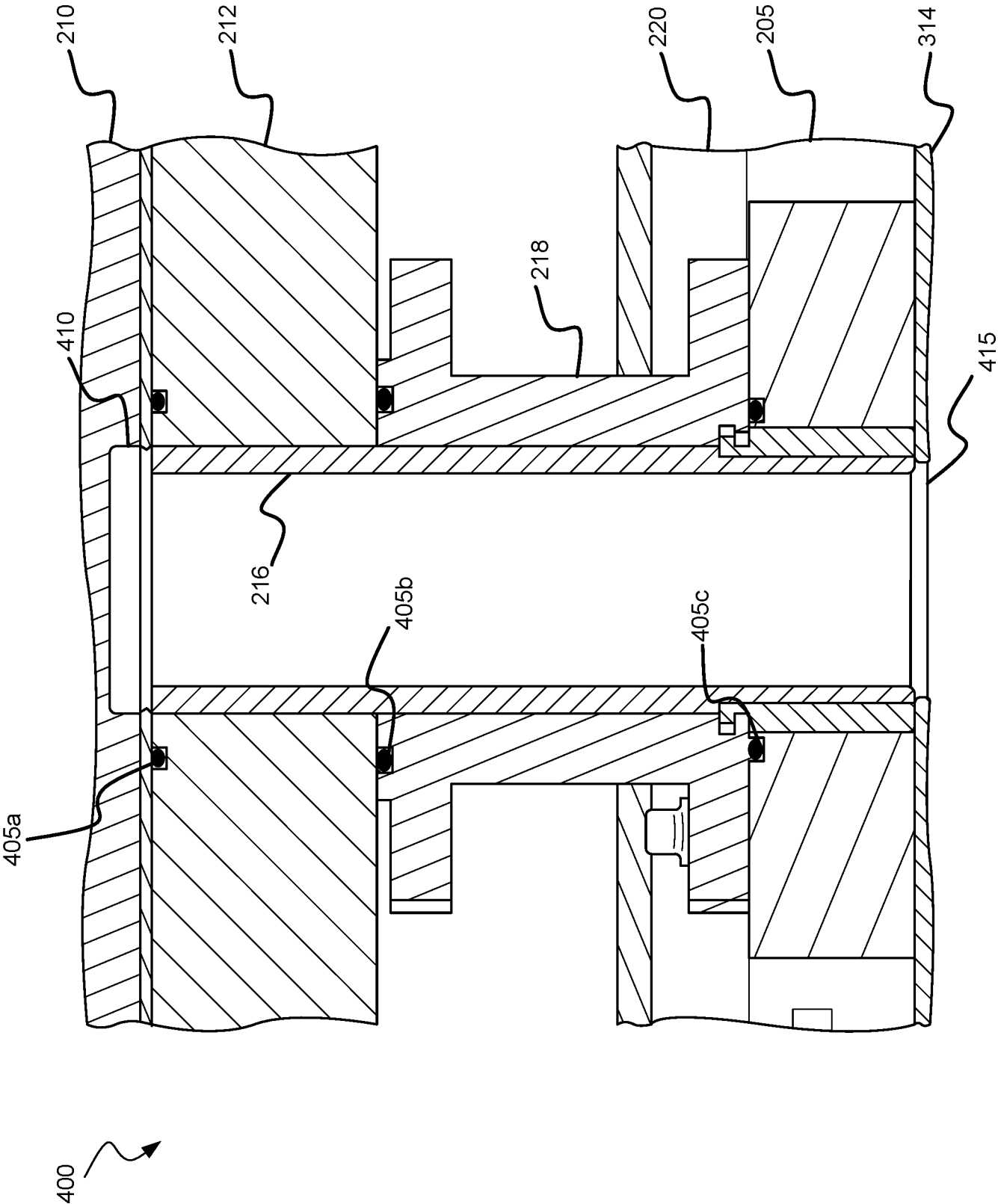


FIG. 4

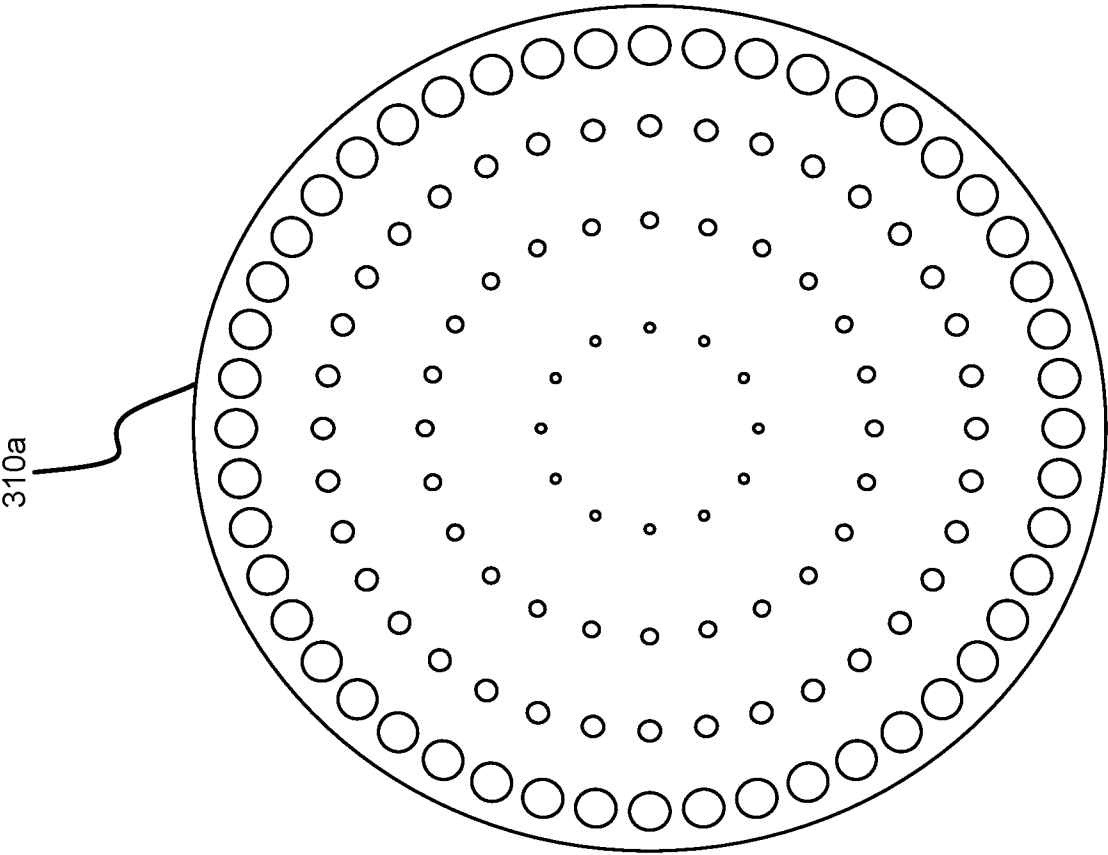


FIG. 5A

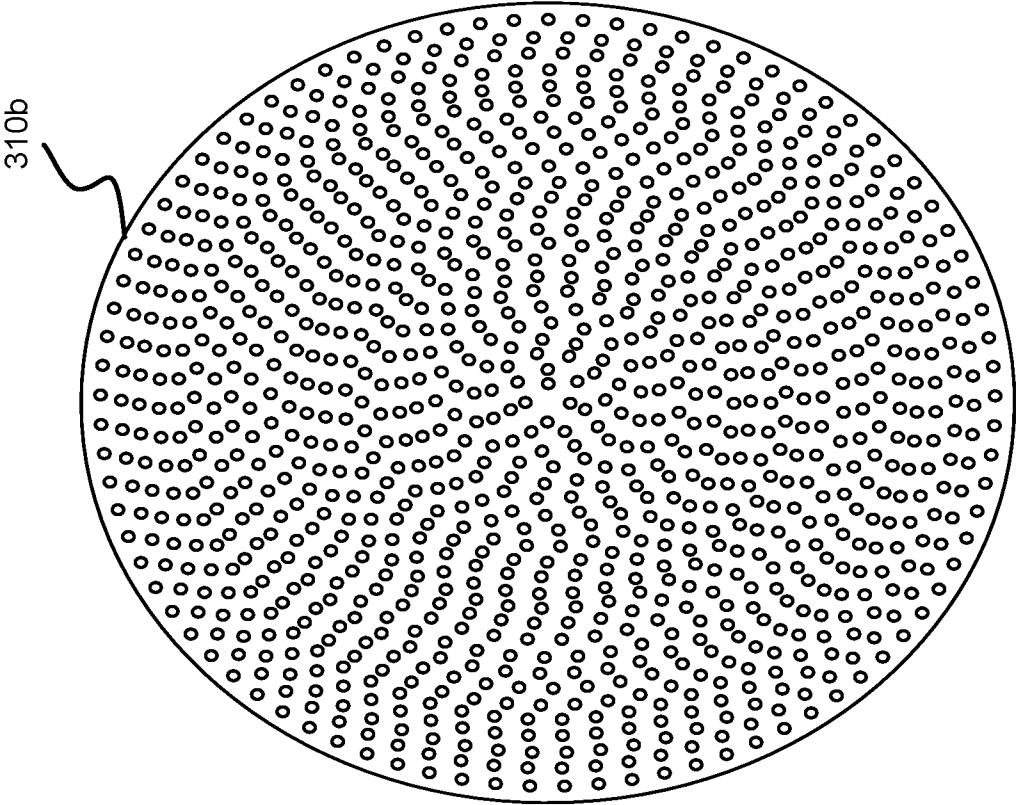


FIG. 5B

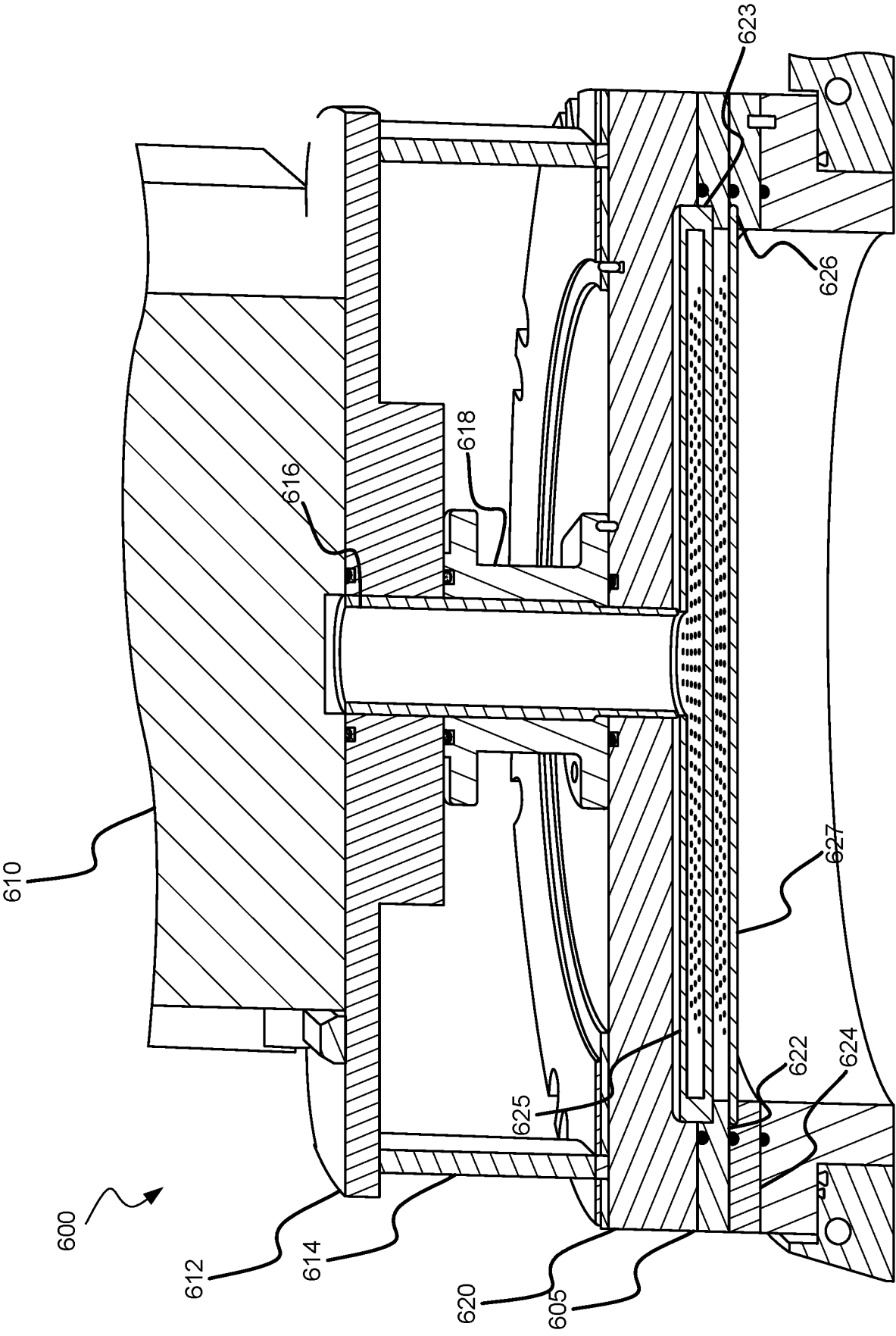


FIG. 6

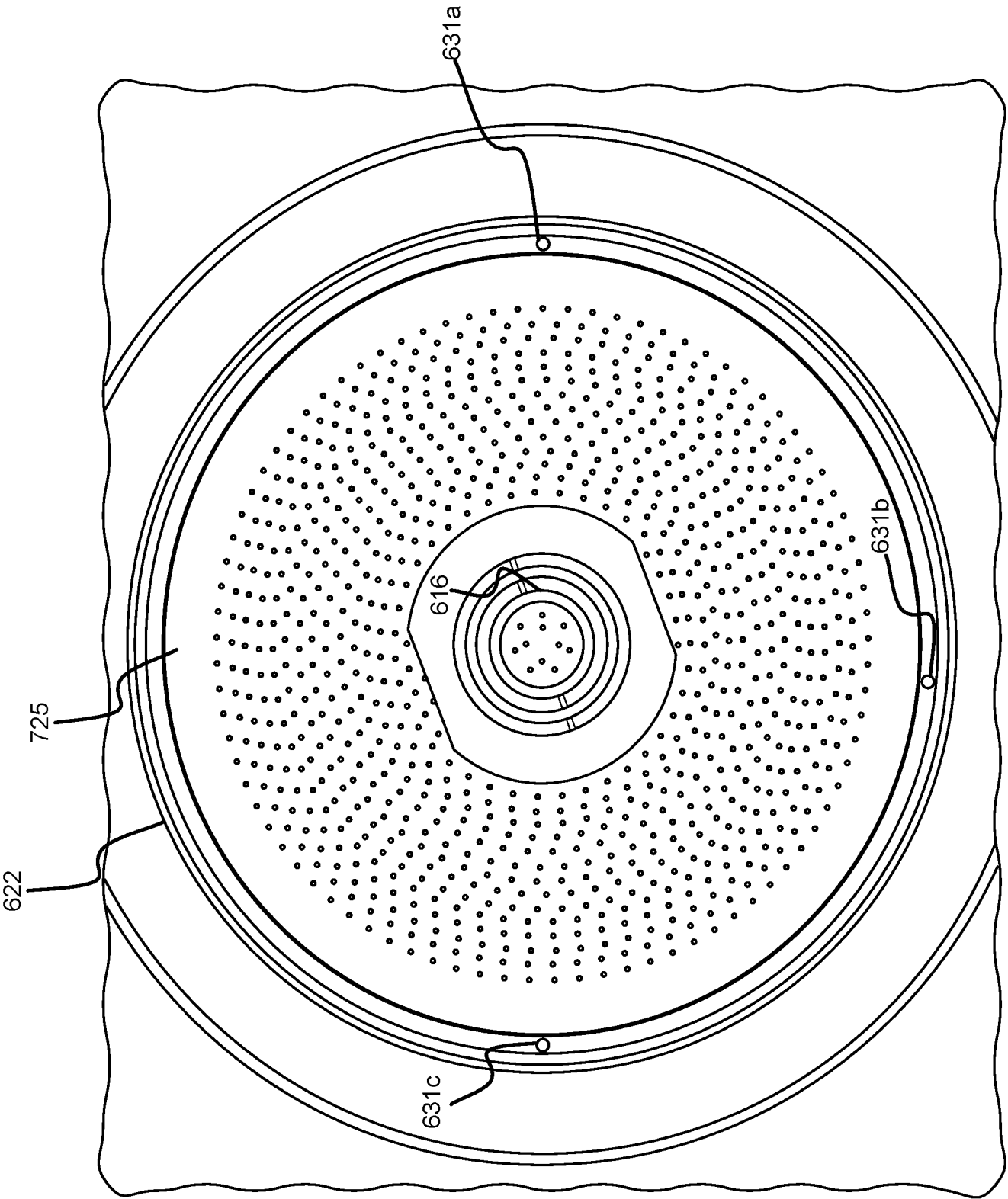


FIG. 7

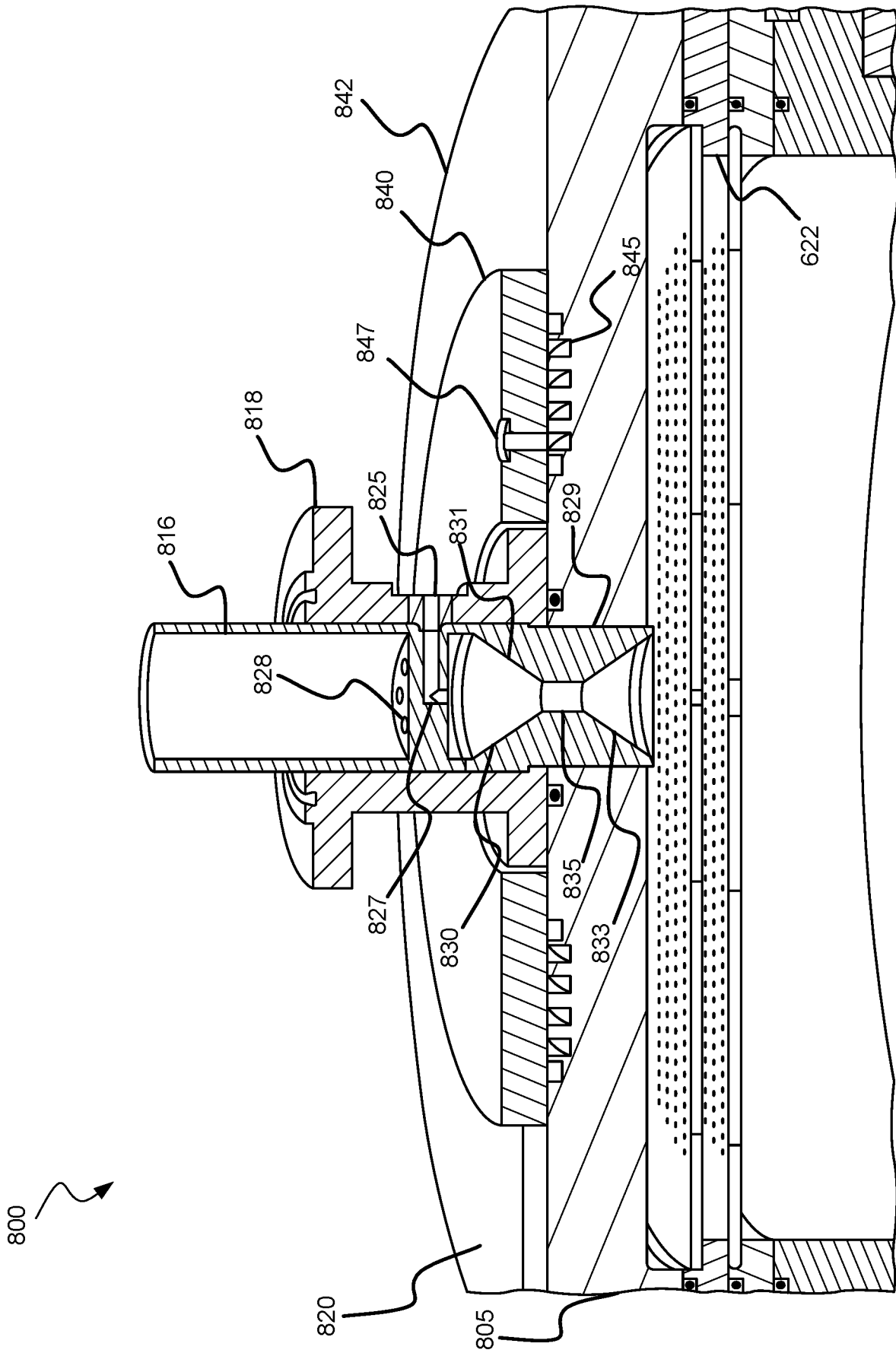


FIG. 8

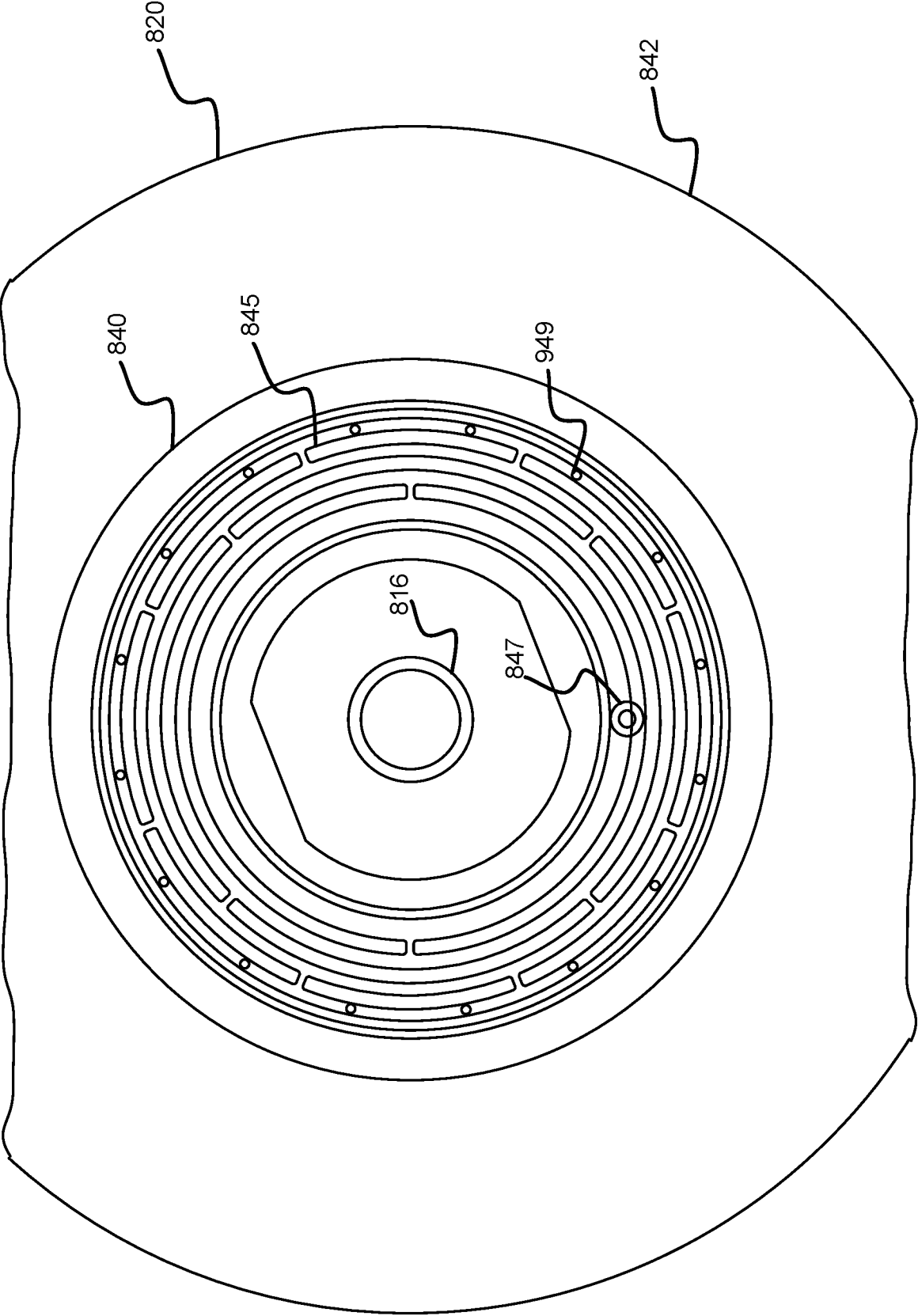


FIG. 9

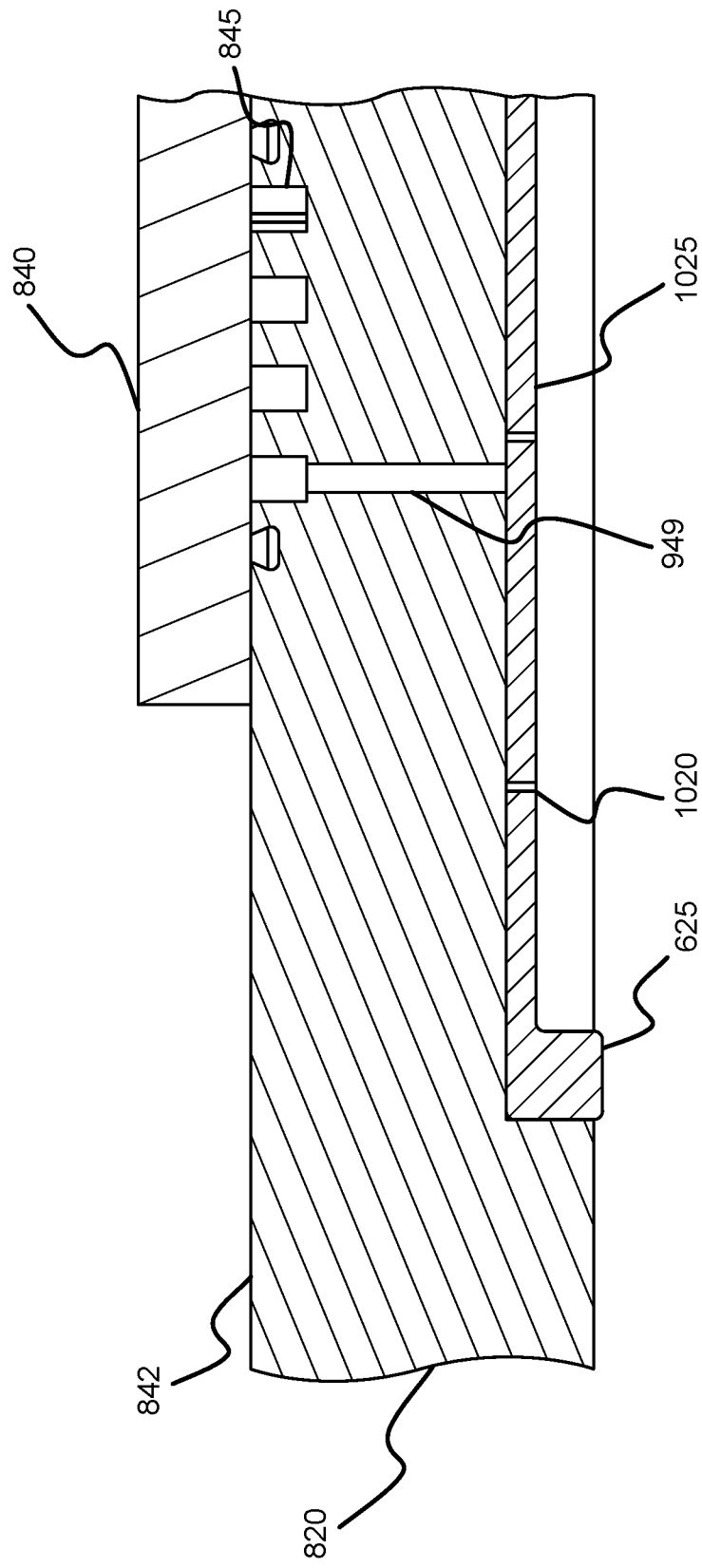
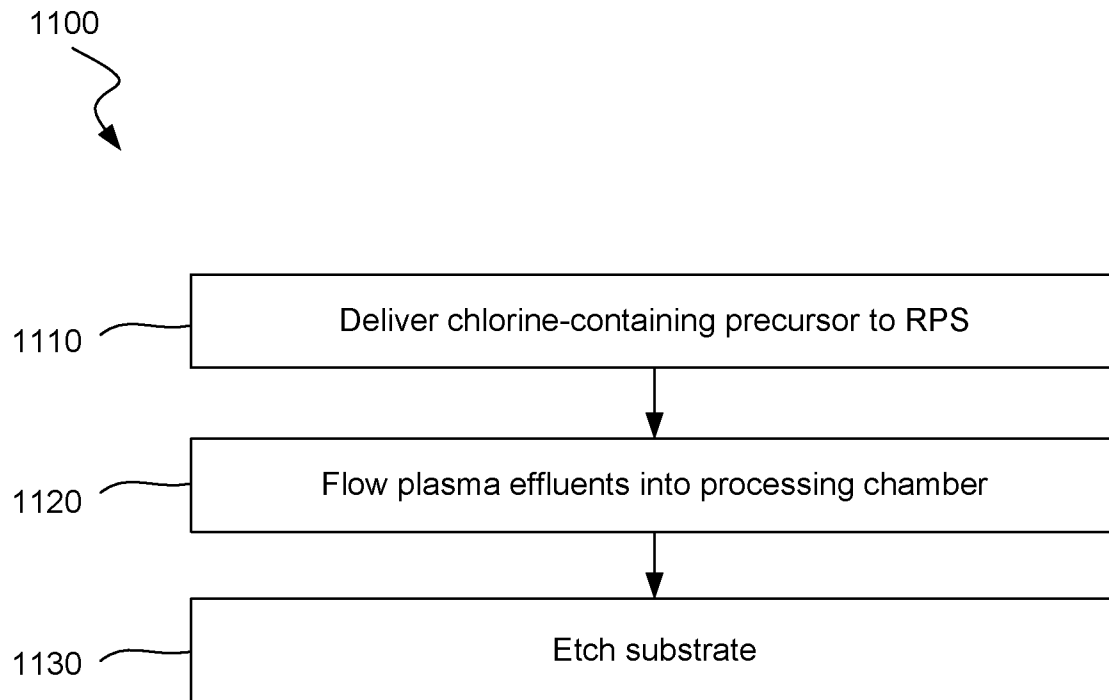


FIG. 10

**FIG. 11**

A. CLASSIFICATION OF SUBJECT MATTER**H01L 21/3065(2006.01)i, H01L 21/67(2006.01)i, H01L 21/683(2006.01)i**

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

H01L 21/3065; H01L 21/302; B08B 3/00; H01L 21/02; C23C 16/44; C01B 33/12; C23C 16/00; C23F 1/08; H01L 21/67; H01L 21/683

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Korean utility models and applications for utility models

Japanese utility models and applications for utility models

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

eKOMPASS(KIPO internal) & Keywords: remote plasma, corrosion, aluminium, quartz, bracket

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2005-0000432 A1 (ERNST KELLER et al.) 06 January 2005 See paragraphs [0032], [0033], [0059], [0061], [0071], [0080], [0107] and figures 1, 4, 7, 13.	8, 12
Y		1, 6, 7, 13-15
A		2-5, 9-11
Y	US 2011-0146909 A1 (HONG SHIH et al.) 23 June 2011 See paragraphs [0034], [0035] and figure 1.	1, 6, 7, 13-15
Y	US 2010-0224324 A1 (SHIGERU KASAI) 09 September 2010 See paragraphs [0041], [0046] and figure 1.	13-15
A	KR 10-2016-0002543 A (SEMES CO., LTD.) 08 January 2016 See the whole document.	1-15
A	JP 4191137 B2 (TOKYO ELECTRON LTD.) 03 December 2008 See paragraphs [0010]-[0030] and figure 1.	1-15



Further documents are listed in the continuation of Box C.



See patent family annex.

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"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

24 August 2017 (24.08.2017)

Date of mailing of the international search report

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Name and mailing address of the ISA/KR

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INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.

PCT/US2017/033362

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